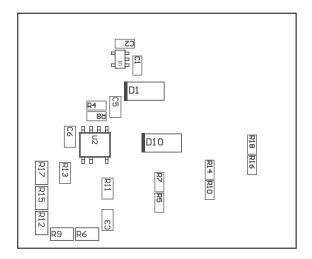


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP11302	REV: A	SVN REV	: Not In VersionControl		
	TID #:					
PLOT NAME = Top Assembly Drawing	GENERATED : 8/25/2	2015 12:55:58	PM	TEXAS INSTRUMENTS		



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP11302 REV: A SVN REV: Not In Version		: Not In VersionControl			
	TID #:					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 8/25/2	2015 12:55:59	PM	TEXAS INSTRUMENTS		

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